



## Material Content Data Sheet



Sales Product Name	TLE4968-1K			Issued		4. November 2019		
MA#	MA001613760							
Package	PG-SC59-3-5			Weight*		13.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.350	2.52	2.52	25208	25208
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		76	
	non noble metal	titanium	7440-32-6	0.005	0.04		379	
	non noble metal	chromium	7440-47-3	0.016	0.11		1138	
	non noble metal	copper	7440-50-8	5.236	37.76	37.92	377615	379208
wire	noble metal	gold	7440-57-5	0.024	0.18	0.18	1760	1760
encapsulation	organic material	carbon black	1333-86-4	0.076	0.55		5508	
	plastics	epoxy resin	-	1.642	11.84		118423	
	inorganic material	silicondioxide	60676-86-0	5.918	42.69	55.08	426872	550803
leadfinish	non noble metal	tin	7440-31-5	0.255	1.84	1.84	18409	18409
plating	noble metal	silver	7440-22-4	0.158	1.14	1.14	11361	11361
glue	plastics	epoxy resin	-	0.032	0.23		2319	
	noble metal	silver	7440-22-4	0.152	1.09	1.32	10932	13251
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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